




IFW

PATENT
Docket No. 20063/OG03-051

**IN THE UNITED STATES PATENT
AND TRADEMARK OFFICE**

Applicant(s):) I hereby certify that this paper and the
) documents referred to as enclosed
) therewith are being deposited with the
) United States Postal Service as first
U.S. Serial No.: 10/747,603) class mail, postage prepaid, in an
) envelope addressed to Commissioner
For: "Methods of Fabricating) for Patents, P.O. Box 1450,
Semiconductor Device Bonding) Alexandria, Virginia 22313-1450 on
Pads") this date:
)
Filed: 12/29/2003) **June 24, 2005**
)
Group Art Unit: 2812)
)
Examiner: Not Yet Assigned) 
) Mark C. Zimmerman
) Attorney for Applicant(s)
) Registration No. 44,006

STATUS LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

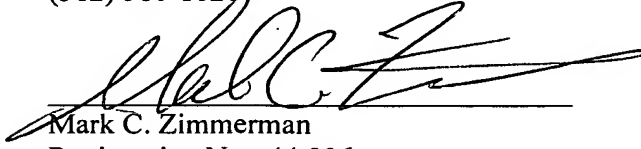
Kindly advise when an Office action can be expected in the above-referenced
matter.

Respectfully submitted,

HANLEY, FLIGHT & ZIMMERMAN, LLC
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June 24, 2005

By:


Mark C. Zimmerman
Registration No.: 44,006